Reply to Non-Final Office Action of January 15, 2008

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior claims, and listings of claims, in the

application:

Listing of Claims

Claim 1 (Previously Presented): A semiconductor light-emitting element mounting member

comprising:

a substrate; and

a metal film formed on a surface of said substrate, formed from Ag, Al, or an alloy

containing said metals, and functioning as an electrode layer for mounting at least one of a

semiconductor light-emitting element and a reflective layer for reflecting light from a

semiconductor light-emitting element;

wherein the thickness of the metal film is 0.5 -  $3~\mu m$  and crystal grains of said metal

or alloy forming said metal film have a particle diameter along a surface plane of said metal film is

no more than  $0.5~\mu m$  and said surface of said metal film has a center-line average roughness Ra of

no more than 0.1 µm.

Claim 2 (Original): A semiconductor light-emitting element mounting member according to

claim 1 wherein an adhesion layer and a barrier layer are formed, in sequence, on said substrate,

with said metal film being formed on said barrier layer.

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Claim 3 (Previously Presented): A semiconductor light-emitting element mounting member

according to claim 1 wherein said metal film is formed as an alloy of at least one of Ag and Al and

other metal, a proportional content of said other metal being 0.001 - 10 percent by weight.

Claim 4 (Original): A semiconductor light-emitting element mounting member according to

claim 3 wherein said other metal is at least one type of metal selected from a group consisting of

Cu, Mg, Si, Mn, Ti, and Cr.

Claim 5 (Canceled).

Claim 6 (Original): A semiconductor light-emitting element mounting member according to

claim 1 wherein said metal film is formed from Al alone or from an alloy of Al and other metal.

Claim 7 (Original): A semiconductor light-emitting element mounting member according to

claim 1 wherein a thermal expansion coefficient of said substrate is 1×10<sup>-6</sup>/K - 10×10<sup>-6</sup>/K.

Claim 8 (Original): A semiconductor light-emitting element mounting member according to

claim 1 wherein a thermal conductivity of said substrate is at least 80 W/mK.

Claim 9 (Original): A semiconductor light-emitting element mounting member according to

claim 1 wherein said semiconductor light-emitting element mounting member is a flat submount.

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Claim 10 (Currently Amended): A semiconductor light-emitting element mounting member

of claim 1 further comprising device wherein a semiconductor light-emitting element is mounted

thereto in a semiconductor light-emitting element mounting member according to claim 1.

Claim 11 (Currently Amended): A semiconductor light-emitting device according to claim

10 wherein the output of said semiconductor light-emitting element is at least 1 W.

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